

### **Amendments to the Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application:

### **Listing of Claims:**

1. **(Currently Amended)** A semiconductor-based device processing apparatus comprising:

a chuck for supporting a wafer; and

a barrier having a first position relative to the wafer wherein the first position relative to the wafer substantially facilitates etch uniformity for a chemically driven etch process, and having a second position relative to the wafer wherein the second position relative to the wafer does not interfere with the etch uniformity of an ion driven etch process, wherein the chuck is moved to establish the first and the second position of the barrier relative to the wafer.

2. **(Previously Presented)** The apparatus as recited in claim 1 wherein the barrier has a top surface and the wafer has a top surface wherein in the second position the top surface of the barrier is not above the top surface of the wafer.

3. **(Original)** The apparatus as recited in claim 2 wherein the first position is substantially above the wafer and the second position is substantially below the wafer.

4. **(Canceled).**

5. **(Original)** The apparatus as recited in claim 1 wherein the barrier surrounds the periphery of the wafer.

6-24 **(Canceled)**.